

MATERIAL DECLARATION SHEET



Material Number	1.5SMBJ12A ~ 1.5SMBJ64A 1.5SMBJ12CA ~ 1.5SMBJ33CA			
Product Line	Semiconductors			
Compliance Date	2021/01/14			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon	0.00461	Silicon	7440-21-3	60.1800%	2.732%	4.539%
				Phosphorus	7723-14-0	0.0100%	0.0005%	
				Boron	7440-42-8	0.0100%	0.0005%	
				Nickel	7440-02-0	14.8000%	0.672%	
				Lead	7439-92-1	12.5000%	0.567%	
				Silicon dioxide	7631-86-9	10.0000%	0.454%	
				Aluminum oxide	1344-28-1	2.5000%	0.1135%	
2	High-melting point Solder paste	solder paste	0.00452	Tin	7440-31-5	5.000%	0.223%	4.451%
				Lead	7439-92-1	92.500%	4.1170%	
				Silver	7440-22-4	2.500%	0.111%	
3	Lead frame / Leads / Disc	N/A	0.03650	Copper	7440-50-8	99.800%	35.867%	35.939%
				Iron	7439-89-6	0.150%	0.054%	
				Phosphorus	7723-14-0	0.050%	0.018%	
				Silica	60676-86-0	76.000%	41.083%	
4	Molding Compound (Plastic Package Only)	Epoxy material	0.05490	Epoxy resin	29690-82-2	12.000%	6.487%	54.057%
				Phenolic resin	9003-35-4	11.000%	5.946%	
				Carbon black	1333-86-4	1.000%	0.5410%	
				Tin (Sn)	7440-31-5	100.000%	1.014%	
5	Plating	Matte-Tin	0.00103	Tin (Sn)	7440-31-5	100.000%	1.014%	1.014%
		Total Weight	0.10156g					

This Document was updated on: 2021/01/14

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements. Please see current Certificate of Compliance for exemption(s) used.